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August 7, 2000

Attorney Docket No.: 06457-017002

Box Patent Application

Commissioner for Patents

Washington, DC 20231

Presented for filing is a new divisional patent application of:

Applicant: DONALD V. SMART

Title: PULSE CONTROL IN LASER SYSTEMS

The prior application is assigned of record to General Scanning, Inc., a Delaware corporation, by virtue of an assignment submitted to the Patent and Trademark Office and recorded on June 12, 1998 at 9274/0059.

Enclosed are the following papers, including those required to receive a filing date under 37 CFR 1.53(b):

	<u>Pages</u>
Specification	13
Claims	7
Abstract	1
Copy of Declaration	1
Drawing(s)	4
Copy of Assignment	2

Enclosures:

- Information Disclosure Statement with PTO Form 1449
- Postcard.

This application is a divisional (and claims the benefit of priority under 35 USC 120) of U.S. application serial no. 09/096,600, filed June 12, 1998. The disclosure of the prior application is considered part of (and is incorporated by reference in) the disclosure of this application.

Basic filing fee	\$690
Total claims in excess of 20 times \$18	\$180
Independent claims in excess of 3 times \$78	\$0
Fee for multiple dependent claims	\$0
Total filing fee:	\$870

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A check for the filing fee is enclosed. Please apply any other required fees or any credits to deposit account 06-1050, referencing the attorney docket number shown above.

If this application is found to be incomplete, or if a telephone conference would otherwise be helpful, please call the undersigned at (202) 783-5070.

Kindly acknowledge receipt of this application by returning the enclosed postcard.

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43. The method of claim 40 wherein the pre-selected pulse shape is a pre-selected peak pulse power.

44. The method of claim 40 wherein the step of pulsing the pulsed laser system comprises micromachining a semiconductor circuit on a silicon substrate.

45. The method of claim 40 wherein the electronic device is a thick-film electrical element.

46. The method of claim 40 wherein the electronic device is a thin-film electrical element.

47. The method of claim 40 wherein the electronic device is a resistor.

48. The method of claim 40 wherein the electronic device is a capacitor.

49. The method of claim 40 wherein the electronic device is a conductive link.

50. The method of claim 40 wherein the step of presetting the pre-selected pulse shape is performed by computer control.

51. The method of claim 40 wherein the pre-selected repetition rate is selected by computer control.

52. The method of claim 40 wherein the laser source comprises a laser pump and a laser rod, and the pulsed laser system comprises a switch that, when closed, causes energy from the laser pump to be stored in the laser and that, when opened, allows energy to be emitted from the laser rod during an emission period.

53. The method of claim 52 wherein:

the pulsed laser system further comprises a reflector interposed between the laser pump and the laser rod, through which energy from the laser pump enters the laser rod, and an output reflector through which energy is emitted from the laser rod; and

the switch is interposed between the laser rod and the output reflector.

54. The method of claim 40 wherein the step of pulsing the pulsed laser system comprises preventing a secondary laser emission from impinging on the workpiece after allowing a primary pulse to impinge on the workpiece.

55. A method of operating a pulsed laser system comprising:

- providing a pulsed laser system comprising a laser source;
- presetting a pre-selected repetition rate at which the pulsed laser system is to be operated, based on known properties of a target material to be processed on a workpiece; and
- pulsing the pulsed laser system with a pre-selected pulse shape selected independently of the pre-selected repetition rate, to cause the laser source to process the target material on the workpiece, while the pre-selected repetition rate remains as preset regardless of the pulse shape.

56. The method of claim 55 wherein the pre-selected pulse width is a pre-selected pulse width.

57. The method of claim 55 wherein the pre-selected pulse shape is a pre-selected pulse energy.

58. The method of claim 55 wherein the pre-selected pulse shape is a pre-selected peak pulse power.

59. The method of claim 55 wherein the step of operating the pulsed laser system comprises micromachining a semiconductor circuit on a silicon substrate.

60. The method of claim 55 wherein the electronic device is a thick-film electrical element.

61. The method of claim 55 wherein the electronic device is a thin-film electrical element.

62. The method of claim 55 wherein the electronic device is a resistor.

63. The method of claim 55 wherein the electronic device is a capacitor.

64. The method of claim 55 wherein the electronic device is a conductive link.

65. The method of claim 55 wherein the step of presetting the pre-selected pulse shape is performed by computer control.

66. The method of claim 55 wherein the pre-selected repetition rate is selected by computer control.

67. The method of claim 55 wherein the laser source comprises a laser pump and a laser rod, and the pulsed laser system comprises a switch that, when closed, causes energy from the laser pump to be stored in the laser and that, when opened, allows energy to be emitted from the laser rod during an emission period.

68. The method of claim 67 wherein:

the pulsed laser system further comprises a reflector interposed between the laser pump and the laser rod, through which energy from the laser pump enters the laser rod, and an output reflector through which energy is emitted from the laser rod; and

the switch is interposed between the laser rod and the output reflector.

69. The method of claim 55 wherein the step of operating the pulsed laser system comprises preventing a secondary laser emission from impinging on a workpiece after allowing a primary pulse to impinge on the workpiece.--

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Attorney's Docket No.: 06457-017002

REMARKS

Applicant submits that all of the claims are in condition for examination, which action is requested. Filed herewith is a check in payment of the excess claims fees required by the above amendments. Please apply any other charges or credits to Deposit Account No. 06-1050.

Respectfully submitted,

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PULSE CONTROL IN LASER SYSTEMS

Background of the Invention

5 This invention relates to controlling pulses in
laser systems and more particularly relates to controlling
the width and energy of pulses at differing repetition rates
during micromachining procedures such as resistor trimming
or capacitor trimming.

10 The pulse width of a laser typically increases with
increased repetition rate (i.e., the rate at which pulses
are emitted by the laser). This is because at high
repetition rates the time to store energy in the laser rod
prior to each pulse is short and at low repetition rates the
15 time to store energy in the laser rod prior to each pulse is
long. Hence, on a per pulse basis, there is great variation
in the energy output and temporal pulse width as the
repetition rate is varied.

20 This effect is due to the fact that the energy that
can be extracted from a laser rod depends on the energy
stored in the rod. For example, at a repetition rate of 30
kilohertz there are only about 33 microseconds available to
store and open a Q-switch to allow a laser pulse to be
emitted, whereas at 1 kilohertz there are about a thousand
25 microseconds available to store and Q-switch. The gain in a
laser is proportional to quantity of energy stored in the
rod. Therefore, when a laser pulse is instigated at a low
repetition rate it sweeps up much more quickly than it would
at a higher frequency because there is more energy stored in
30 the rod, resulting in a shorter temporal pulse width.

 For a given energy per pulse the peak power varies
inversely with the laser pulse width. Therefore, the peak
power of a 300-nanosecond pulse is much less than the peak
power of a 100-nanosecond pulse having the same total

energy. The total energy per pulse delivered to the workpiece is typically controlled by a device that attenuates the beam; laser pulses at 1 kilohertz would be attenuated more than laser pulses at 10 kilohertz in order
5 for the pulses in each instance to have the same total energy.

It is possible to widen laser pulses provided by a given laser at low repetition rates by lowering the energy stored in the laser rod when the laser is operated at low
10 repetition rates. This can be accomplished by lowering the amount of energy that enters the rod from the laser pump. The Light Wave Electronics Model 110 laser works according to this principle.

It is also possible to ensure similar pulse widths at differing repetition rates by pumping energy into the laser rod prior to each laser pulse for about the same storage time period regardless of the repetition rate. After this high energy storage time but prior to opening of the Q-switch, the energy that is pumped into the laser rod
15 is reduced to a level that is just above a threshold required to compensate for losses in the energy stored in the laser rod. This reduced energy level can be maintained until the Q-switch is opened to allow a pulse to be released from the laser rod.
20

General Scanning's M320 pulsed laser system is an example of a system that does not ensure similar pulse widths at differing repetition rates. In this system, an acousto-optic modulator (AOM), is placed between the laser and the workpiece. As the laser scans over a workpiece, the
25 acousto-optic modulator blocks laser pulses from impinging on the workpiece except when a laser pulse is needed to remove a link on the workpiece. In order to remove a link, the acousto-optic modulator allows a single pulse, emitted
30

immediately after opening of the Q-switch, to impinge on the link. The acousto-optic modulator can allow only a fraction of the energy of the pulse to impinge on the link, as desired.

5 Togari et al., U.S. Patent No. 5,719,372 describes a laser marking system in which laser pulses create holes in a workpiece that form a marking. Each emission period, during which the Q-switch is off (open), is sufficiently long to allow the laser to emit a primary emission pulse and a
10 plurality of secondary emission pulses, all of which impinge upon the workpiece. The intensities of these primary and secondary emission pulses are less than the intensity of the single emission pulse that would be emitted if the emission period were shorter and the repetition rate kept the same.
15 The low-power secondary emissions deliver extra energy to the workpiece. The patent claims that the low-power secondary emissions result in improved visibility of marking lines in a workpiece that includes a resin film containing carbon.

20 Summary of the Invention

One aspect of the invention features a pulsed laser system that includes a laser pump (e.g., a continuous wave (CW) pump), a laser rod, a reflector interposed between the laser pump and the laser rod, through which energy from the
25 laser pump enters the laser rod, an output reflector through which energy is emitted from the laser rod, and a switch (e.g., a Q-switch) interposed between the laser rod and the output reflector. Further there is a control device, which may be external to the laser resonator. The Q-switch, when
30 closed, causes energy to be stored in the laser rod and, when opened, allows energy to be emitted from the laser rod during an emission period. The control device allows a primary laser pulse emitted from the laser rod during the

emission period to impinge on a workpiece and prevents at least a portion of secondary laser emission occurring after the primary pulse during the emission period from impinging on the workpiece.

5 The diode pumped laser technology according to the invention provides flexibility in and control over the pulse width, along with the repetition rate, in order to optimize performance. The invention makes it possible to use a laser that has short pulse widths at high repetition rates to
10 process a workpiece (for example, to perform resistor trimming) at low repetition rates without emitting unduly short pulses. The low repetition rates may be especially useful for certain applications such as trimming high valued resistors.

15 The invention does not require any reduction in the output of the laser pump in order to provide wide pulses at low repetition rates. Thus, it is not necessary to redesign or otherwise accommodate the power supply electronics and feedback circuitry that are designed to ensure a stable
20 output of the laser pump. Also, the invention does not require energy to be pumped into the laser rod at a reduced level during the portion of the emission period following emission of the primary laser pulse. Thus, the invention need not concern itself with errors that might be introduced
25 into the total energy stored in the laser rod following emission of the primary laser pulse, which errors would be especially significant at low attenuation.

 Because a control device is provided that prevents unwanted output emitted during the emission period after
30 emission of the primary pulse from impinging on the workpiece, this portion of the laser output does not affect the temperature of the workpiece, and therefore does not affect measurements that might take place prior to each

primary pulse, which may be temperature-sensitive, and does not affect performance of the workpiece. For example, in trimming of thick-film resistors, resistance measurements might take place immediately prior to each primary pulse.

5 In micromachining of a semiconductor circuit on a silicon substrate, elimination of secondary pulses and a continuous wave output can prevent undue heating of the silicon substrate and thereby protect the silicon substrate against damage.

10 Another aspect of the invention features a method in which the pulsed laser system is operated over a range of repetition rates, so as to cause laser energy to be emitted during a plurality of emission periods at each repetition rate. At least a portion of the laser energy emitted during
15 the emission periods is directed toward the target structure. The switch is closed for a fixed, predetermined period of time prior to each emission period regardless of repetition rate of the primary laser pulse within the range of repetition rates. The pump is operated continuously at
20 constant power.

Numerous other features, objects, and advantages of the invention will become apparent from the following detailed description when read in connection with the accompanying drawings.

25 Brief Description of the Drawings

FIG. 1 is a block diagram that discloses the major components of a laser system according to the invention.

FIG. 2 is a block diagram that discloses the major components of an alternative laser system according to the
30 invention.

FIG. 3 is a set of waveforms illustrating operation of the laser system of FIG. 1 at a high, fixed repetition rate, and also at a low repetition rate.

FIG. 4 is a diagram illustrating the power of the output of the laser system of FIG. 1 as a function of time in the absence of an acousto-optic modulator.

FIG. 5 is a diagram similar to FIG. 4, having a reduced time scale.

FIG. 6 is a diagram illustrating the power of the output of the laser system of FIG. 1 as a function of time, where an acousto-optic modulator is used to dump a continuous wave output from the laser onto a heat sink.

Thus, FIG. 6 is the same as FIG. 4 with the secondary, unwanted pulses removed.

Detailed Description

In trimming of thick-film resistors, the optimal peak laser pulse power, pulse width, and pulse energy depends on the type and thickness of the resistor paste material.

For example, high-ohm pastes generally contain less metal than low-ohm pastes and are generally thicker than low-ohm pastes. High-ohm pastes generally require a longer laser pulse width than low-ohm pastes because heat conduction in the semi-insulating high-ohm pastes generally takes more time than in low-ohm pastes.

In contrast, low-ohm pastes tend to contain a great deal of metal. These pastes have a tendency to conduct heat laterally away from the kerf (cut) produced by the laser pulse. Short laser pulses tend to limit the likelihood of this lateral conduction in these low-ohm pastes.

Thick-film resistors typically are about 5 microns thick, and therefore it takes time for a laser pulse to heat through the entire resistor due to thermal diffusivity. Typically, 100 nanoseconds is a good pulse width for such a resistor, but below 70 nanoseconds the pulse might not have enough time to penetrate all the way through the resistor

and hence might leave some resistor material at the bottom of the kerf. This material can promote leakage currents and compromise resistor performance. At a pulse width of 300 nanoseconds, on the other hand, the resistor will be

5 penetrated completely, but heat might tend to dissipate laterally through the resistor because the pulse is so long. This lateral heat conduction can result in a melting zone and residue at the edge of the resistor kerf, which can change the temperature coefficient of resistance (TCR) and

10 cause microcracking. Microcracking can, in turn, cause long-term resistance drift.

In addition to pulse width, the energy of the laser pulses is also important because a certain amount of energy is required to vaporize the resistor material.

15 Also, the speed of trimming is important, with high trimming rates typically being desirable. The ultimate limit to the trimming rate is a function of the amount of energy per pulse that is to be delivered to the resistor. This energy per pulse is approximately 200 to 300

20 microjoules per pulse, depending on the type of resistor paste that is used. For a laser having an average power of 7 watts, if the desired energy per pulse is 200 microjoules, the repetition rate of the pulses cannot exceed 7 watts divided by 0.0002 joules, or 35 kilohertz. If the desired

25 energy per pulse is 300 microjoules then the repetition rate of the pulses cannot exceed 7 watts divided by 0.0003 joules, or about 23 kilohertz. The higher energy per pulse of 300 microjoules would typically be used for low-ohm materials, which are ordinarily trimmed at lower repetition

30 rates anyway.

The dynamic pulse width control technique described below is implemented using a high-power, short pulse width, diode-pumped laser. This laser system can provide

30-nanosecond pulses at low repetition rates and
125-nanosecond pulses at 50 kilohertz, in comparison to
lamp-pumped laser systems that provide 70-nanosecond pulses
at low repetition rates and 300-nanosecond pulses at 40
5 kilohertz. Nevertheless, the dynamic pulse width control
technique can alternatively be implemented using a lamp-
pumped laser system.

The dynamic pulse width control described below can
allow a laser, such as the Spectra Physics DPL laser system,
10 for example, to provide 125-nanosecond pulse widths at any
repetition rate, from a single pulse to 50 kilohertz.

While high repetition rates are typically desirable,
such a laser might be operated at low repetition rates so as
to allow resistance measurements to be made, between the
15 pulses, while the resistor is being trimmed. If the
resistance to be measured is very high, then it might
typically take a relatively long time to perform each
measurement accurately, and thus a lower repetition rate
might be desirable. According to the invention, such a
20 laser can be operated at a low repetition rate of about 1
kilohertz, for example, at a pulse width of about 125
nanoseconds, rather than 30 nanoseconds (which would be
typical without the dynamic pulse width control). The
dynamic pulse width control ensures that the pulse width is
25 long enough to cut through the resistor material to the
bottom of the resistor.

With reference to FIG. 1, laser 10 includes an
energy storage rod 12 and a diode pump 14, which is pumped
continuously. Energy from the diode pump enters the laser
30 rod 12 through a lens 16 and a 100-percent reflector 18. An
acousto-optical Q-switch 20, which is essentially an optical
switch, is switchable on and off to cause energy to remain
stored in laser rod 12. When Q-switch 20 is turned on,

lasing action is inhibited, thereby allowing energy from the laser diode 14 to be delivered to the rod 12. The energy stored in laser rod 12 will increase, because Q-switch 20 blocks emission of the laser beam. About a microsecond or two after Q-switch 20 is turned off (opened) a laser pulse is emitted from laser rod 12 through reflector 24. An X-scanning mirror and a Y-scanning mirror (not shown) move the pulsed laser beam to perform trimming of a thick-film resistor.

The period of time during which Q-switch 20 is off is the "emission period." The rate at which Q-switch 20 is activated is known as the "repetition rate."

In one application of the resistor trimming system of FIG. 1, laser 10 has an intrinsically short pulse width at all repetition rates. However, the energy, pulse width, and peak power of the laser pulse depend upon the amount of energy storage. At low repetition rates the energy storage is high and therefore the pulse width is short and the energy per pulse and peak power are high. As is explained in detail below, during operation of the resistor trimming system at low repetition rates, Q-switch 20 remains open after the laser pulse subsides, and a secondary emission that includes a series of secondary pulses and continuous wave (CW) output is emitted from laser 10. These secondary pulses result from the fact that energy is continuously being pumped into energy storage rod 12 by diode pump 14. Whenever the stored energy resulting from this continuous input exceeds a threshold (the minimum energy required to overcome losses in the energy storage rod system), a secondary pulse is emitted.

The energy of the primary pulse is essentially equal to the power of pump diode laser 10 multiplied by the storage time during which the Q-switch RF power is on,

causing the Q-switch to be closed. If the storage time is about 30 microseconds and the power of the laser is about 7 watts, the total energy in the primary pulse is about 210 microjoules.

5 At one kilohertz, the primary pulse as well as the continuous wave output together have a total energy far in excess of 210 microjoules. The primary pulse output is deflected towards the workpiece by an acousto-optic modulator (AOM) 26, which operates in synchronization with
10 Q-switch 20. The acousto-optic modulator 26 is sufficiently fast in operation to allow the primary laser pulses to deflect to the workpiece and then, by switching off, to dump the continuous wave output and secondary pulses from the short-pulse laser onto a heat sink 28. The acousto-optic
15 modulator 26 deflects the primary laser pulses with at least eighty percent efficiency, and more preferably about ninety percent efficiency or higher, and all of the continuous wave output and secondary pulses of short-pulse laser 10 are dumped onto heat sink 28.

20 Other optical shutters, such as an electro-optic modulator, a liquid crystal modulator, or a high-speed optical switch, may be substituted for acousto-optic modulator 26.

25 According to an alternate method, the primary beam passes through acousto-optic modulator 26, which deflects the unwanted continuous wave output and secondary pulses with ninety percent efficiency as shown in FIG. 2. The method to be used is determined by the nature of the micromachining application. Thus, according to the method
30 of FIG. 2, an optical shutter diffracts, deflects, redirects, or otherwise shutters unwanted laser output away from the workpiece, whereas according to the method of FIG. 1, an optical shutter diffracts, deflects, redirects, or

otherwise shutters desired laser output toward the workpiece.

FIG. 3 illustrates operation of the mechanism for dynamic pulse width control using the primary beam deflection technique as shown in FIG. 1. The top three waveforms of FIG. 3 illustrate operation of the short-pulse laser at a high, fixed repetition rate without the dynamic pulse width control. In this case the Q-switch is operated at the maximum desired repetition rate (40 Khz is shown for this example). The rise time of a laser trigger pulse 30 triggers activation of an RF Q-switch control signal 32, which in turn is applied to the Q-switch to control the on/off state of the Q-switch. While RF Q-switch control signal is activated 32, the RF signal, which is applied to the Q-switch, causes the Q-switch to be in its "on" (closed) state, and the Q-switch blocks emission of the laser beam. This causes energy to be stored in the laser rod. The falling of laser trigger pulse 30 causes RF Q-switch control signal 32 to be de-activated, and because there is no RF signal applied, the Q-switch is caused to be in its "off" (open) state. This causes optical power to build up within the laser cavity (the laser cavity consists of everything located between the 100 percent reflector and the output mirror), and a short time later a laser pulse 34 is emitted during the "emission period." After the emission period, another laser trigger pulse 30 activates RF Q-switch control signal 32 again to cause energy to be stored in the laser rod. At this high repetition rate, the "on" time for RF Q-switch control signal 32 is set to allow the maximum laser storage time between pulses 34. For example, at a repetition rate of 40 kilohertz, the storage time would be about 25 microseconds minus the time required for a pulse 34 to build up in the laser cavity and emit (which is about two

to three microseconds). In alternative embodiments, the Q-switch may be an electro-optical Q-switch, and a high-voltage Q-switch control signal may be used instead of an RF Q-switch control signal.

5 The bottom five waveforms in FIG. 3 illustrate operation of the short-pulse laser at a low, fixed repetition rate using the dynamic pulse width control. RF Q-switch control signal 32 is activated only for a period of time necessary to provide the desired energy storage per pulse and the desired pulse width, which, for this example, is the same energy storage per pulse and pulse width as in the high-repetition-rate example of the top three drawings in FIG. 3. After the time required for energy storage has elapsed, RF Q-switch control signal 32 is deactivated, which causes the Q-switch to be turned off so as to allow the laser to emit an output. The Q-switch is maintained in its off state until storage for the next emission period is desired. According to this method, the energy storage time corresponds to the desired energy per pulse and the desired pulse width. At low repetition rates, as shown in the bottom five waveforms in FIG. 3, the laser will build up and lase in a continuous wave mode output 38 during the emission period, after the primary pulse 36 has been emitted. The output 38 after the primary pulse consists of a series of secondary pulses emitted from the laser followed by a CW output. In the embodiment of FIG. 1, an acousto-optic modulator signal 40 triggers the acousto-optic modulator just before the primary pulse 36 is to be emitted, in order to deflect the primary pulse towards the resistor, and then switches the AOM off so that the unwanted secondary and CW output is dumped on the heat sink as illustrated in FIG. 1. Accordingly, unwanted heating of the resistor to be trimmed is prevented.

FIGS. 4 and 5 illustrate the power of the laser output, including primary pulse 36, and secondary pulses and continuous wave output 38, as a function of time in the absence of an acousto-optic modulator. FIG. 6 illustrates the power of the laser output where the acousto-optic modulator has dumped the continuous wave output from the laser onto a heat sink.

The operator can choose a desired laser pulse width by computer control. The computer is preprogrammed using a look-up table to provide the correct Q-switch storage time for the desired laser pulse width. The computer also provides the correct timing signal for the AOM deflector. Once the operator has chosen a desired pulse width, then the laser can be operated at any repetition rate below the maximum repetition rate that corresponds with this storage time, without change in the total energy per pulse or the pulse width. Thus, the energy delivered to the resistor, the pulse width, and the peak power are fixed at constant values over all repetition rates.

There have been described novel and improved apparatus and techniques for controlling pulses in laser systems. It is evident that those skilled in the art may now make numerous uses and modifications of and departures from the specific embodiment described herein without departing from the inventive concept. For example, while applications of the apparatus to thick-film resistor trimming have been disclosed, other applications of the technology are also possible, such as thick-film capacitor trimming, micro-machining of semiconductor circuits on silicon substrates, thin-film trimming of resistors or capacitors, link blowing, etc.

What is claimed is:

1 1. A pulsed laser system comprising:
2 a laser pump;
3 a laser rod;
4 a reflector interposed between the laser pump and
5 the laser rod, through which energy from the laser pump
6 enters the laser rod;
7 an output reflector through which energy is emitted
8 from the laser rod;
9 a switch interposed between the laser rod and the
10 output reflector that, when closed, causes energy to be
11 stored in the laser rod for a desired period of time and
12 that, when opened, allows energy to be emitted from the
13 laser rod during an emission period;
14 a control device constructed to allow a primary
15 laser pulse emitted from the laser rod during the emission
16 period to impinge on a workpiece and to prevent at least a
17 portion of secondary laser emission occurring after the
18 primary pulse during the emission period from impinging on
19 the workpiece.

1 2. The pulsed laser system of claim 1 wherein the
2 control device comprises an optical shutter.

1 3. The pulsed laser system of claim 1 wherein the
2 optical shutter comprises an acousto-optic modulator, an
3 electro-optic modulator, a liquid crystal modulator, or a
4 high-speed optical switch.

1 4. The pulsed laser system of claim 1 wherein the
2 control device prevents the secondary laser emission from
3 impinging on the workpiece by diffracting, deflecting,
4 redirecting, or shuttering unwanted secondary laser emission
5 away from the workpiece.

1 5. The pulsed laser system of claim 1 wherein the
2 control device allows the primary laser pulse to impinge on
3 the workpiece by diffracting, deflecting, redirecting, or
4 shuttering the primary pulse toward the workpiece.

1 6. The pulsed laser system of claim 1 wherein the
2 control device prevents more than eighty percent of the
3 secondary laser emission occurring during the emission
4 period after emission of the primary pulse from impinging on
5 the workpiece.

1 7. The pulsed laser system of claim 1 wherein the
2 control device begins preventing secondary laser emission
3 occurring during the emission period from impinging on the
4 workpiece immediately after emission of the primary pulse.

1 8. The pulsed laser system of claim 1 wherein the
2 laser pump comprises a diode pumped system.

1 9. The pulsed laser system of claim 1 wherein the
2 laser pump comprises a lamp pumped system.

1 10. The pulsed laser system of claim 1 wherein the
2 switch is a Q-switch.

1 11. The pulsed laser system of claim 10, wherein
2 the Q-switch is configured to close when it receives a
3 control signal and to open when the control signal is not
4 applied to the Q-switch.

1 12. The pulsed laser system of claim 11, wherein
2 the control signal is a high-frequency signal.

1 13. The pulsed laser system of claim 11, wherein
2 the control signal is a high-voltage signal.

1 14. The pulsed laser system of claim 11, wherein
2 the control signal is triggered by a trigger signal.

1 15. The pulsed laser system of claim 1, wherein the
2 switch is arranged to be closed for a fixed, predetermined
3 period of time regardless of repetition rate of the primary
4 laser pulse, over a range of repetition rates.

1 16. The pulsed laser system of claim 15, wherein,
2 at low repetition rates of the primary laser pulse, the
3 control device prevents the secondary laser emission
4 occurring after emission of the primary pulse from impinging
5 on the workpiece, and, at high repetition rates of the
6 primary laser pulse, there is no secondary laser emission
7 occurring during the emission period after emission of the
8 primary pulse.

1 17. The pulsed laser system of claim 1, wherein the
2 laser pump is constructed for continuous operation.

1 18. A method of operating a pulsed laser system
2 comprising the steps of:
3 providing a pulsed laser system comprising a laser
4 pump, a laser rod, a reflector interposed between the laser
5 pump and the laser rod, through which energy from the laser
6 pump enters the laser rod, an output reflector through which
7 energy is emitted from the laser rod, and a switch
8 interposed between the laser rod and the output reflector
9 that, when closed, causes energy to be stored in the laser
10 rod for a desired period of time and that, when opened,

11 allows energy to be emitted from the laser rod during an
12 emission period;
13 operating the pulsed laser system so as to cause
14 laser energy to be emitted during a plurality of emission
15 periods;
16 allowing a primary laser pulse emitted from the
17 laser rod during each emission period to impinge on a
18 workpiece; and
19 preventing at least a portion of secondary laser
20 emission occurring during each emission period after
21 emission of the primary pulse from impinging on the
22 workpiece.

1 19. The method of claim 18, further comprising the
2 step of closing the switch for a fixed, predetermined period
3 of time regardless of repetition rate of the primary laser
4 pulse, over a range of repetition rates.

1 20. The method of claim 19, wherein the fixed,
2 predetermined period of time is the longest energy storage
3 period that can be implemented at the highest repetition
4 rate of the range of repetition rates.

1 21. The method of claim 18, wherein the step of
2 preventing the secondary laser emission occurring during the
3 emission period after emission of the primary pulse from
4 impinging on the workpiece is performed at low repetition
5 rates of the primary laser pulse, and wherein, at high
6 repetition rates of the primary laser pulse, there is no
7 secondary laser emission occurring during the emission
8 period after emission of the primary pulse.

1 22. The method of claim 18, wherein the step of
2 allowing the primary laser pulses to impinge on a workpiece
3 comprises micromachining a worksurface with a controlled
4 laser pulse width.

1 23. The method of claim 22, wherein the step of
2 micromachining a worksurface comprises micromachining a
3 semiconductor circuit on a silicon substrate.

1 24. The method of claim 18, wherein the step of
2 allowing the primary laser pulses to impinge on a workpiece
3 comprises trimming of a trimmable component.

1 25. The method of claim 24, wherein the step of
2 allowing the primary laser pulses to impinge on a workpiece
3 comprises trimming of a thick-film electrical element.

1 26. The method of claim 24, wherein the step of
2 allowing the primary laser pulses to impinge on a workpiece
3 comprises trimming of a thin-film electrical element.

1 27. The method of claim 24, wherein the step of
2 allowing the primary laser pulses to impinge on a workpiece
3 comprises trimming of a resistor.

1 28. The method of claim 24, wherein the step of
2 allowing the primary laser pulses to impinge on a workpiece
3 comprises trimming of a capacitor.

1 29. The method of claim 24, wherein the step of
2 operating the pulsed laser system comprises operating the
3 laser pump continuously.

1 30. A method of operating a pulsed laser system,
2 comprising the steps of:
3 providing a pulsed laser system comprising a laser
4 pump, a laser rod, a reflector interposed between the laser
5 pump and the laser rod, through which energy from the laser
6 pump enters the laser rod, an output reflector through which
7 energy is emitted from the laser rod, and a switch
8 interposed between the laser rod and the output reflector
9 that, when closed, causes energy to be stored in the laser
10 rod for a desired period of time and that, when opened,
11 allows energy to be emitted from the laser rod during an
12 emission period; and
13 operating the pulsed laser system, over a range of
14 repetition rates, so as to cause laser energy to be emitted
15 during a plurality of emission periods at each repetition
16 rate, at least a portion of the laser energy emitted during
17 the emission periods being directed toward the target
18 structure;
19 the step of operating the pulsed laser system
20 comprising closing the switch for a fixed, predetermined
21 period of time prior to each emission period regardless of
22 repetition rate of the primary laser pulse within the range
23 of repetition rates;
24 the step of operating the pulsed laser system
25 further comprising operating the pump continuously at
26 constant power.

1 31. The method of claim 30, wherein the step of
2 directing at least a portion of the laser energy emitted
3 during the emission periods toward the target structure
4 comprises performing functional or passive trimming of the
5 target structure.

1 32. The method of claim 30, wherein the step of
2 operating the pulsed laser system comprises trimming of a
3 trimmable component.

1 33. The method of claim 32, wherein the step of
2 operating the pulsed laser system comprises trimming of a
3 thick-film electrical element.

1 34. The method of claim 32, wherein the step of
2 operating the pulsed laser system comprises trimming of a
3 thin-film electrical element.

1 35. The method of claim 32, wherein the step of
2 operating the pulsed laser system comprises trimming of a
3 resistor.

1 36. The method of claim 32, wherein the step of
2 operating the pulsed laser system comprises trimming of a
3 capacitor.

1 37. The method of claim 32, wherein the step of
2 operating the pulsed laser system comprises micromachining a
3 worksurface.

1 38. The method of claim 37, wherein the step of
2 micromachining a worksurface comprises micromachining a
3 semiconductor circuit on a silicon substrate.

1 39. The method of claim 32, wherein the step of
2 operating the pulsed laser system comprises operating the
3 laser pump continuously.

PULSE CONTROL IN LASER SYSTEMS

Abstract of the Disclosure

A pulsed laser system includes a laser pump, a laser rod, a reflector interposed between the laser pump and the laser rod, through which energy from the laser pump enters the laser rod, an output reflector through which energy is emitted from the laser rod, a switch interposed between the laser rod and the output reflector, and a control device. The switch, when closed, causes energy to be stored in the laser rod and, when opened, allows energy to be emitted from the laser rod during an emission period. The control device allows a primary laser pulse emitted from the laser rod during the emission period to impinge on a workpiece and blocks from the workpiece secondary laser emission occurring during the emission period after emission of the primary pulse. The pulsed laser system is operated over a range of repetition rates, so as to cause laser energy to be emitted during a plurality of emission periods at each repetition rate. At least a portion of the laser energy emitted during the emission periods is directed toward the target structure in order to perform passive or functional trimming of the target structure. The switch is closed for a fixed, predetermined period of time prior to each emission period regardless of repetition rate of the primary laser pulse within the range of repetition rates in order to store energy in the laser rod. The pump is operated continuously at constant power.

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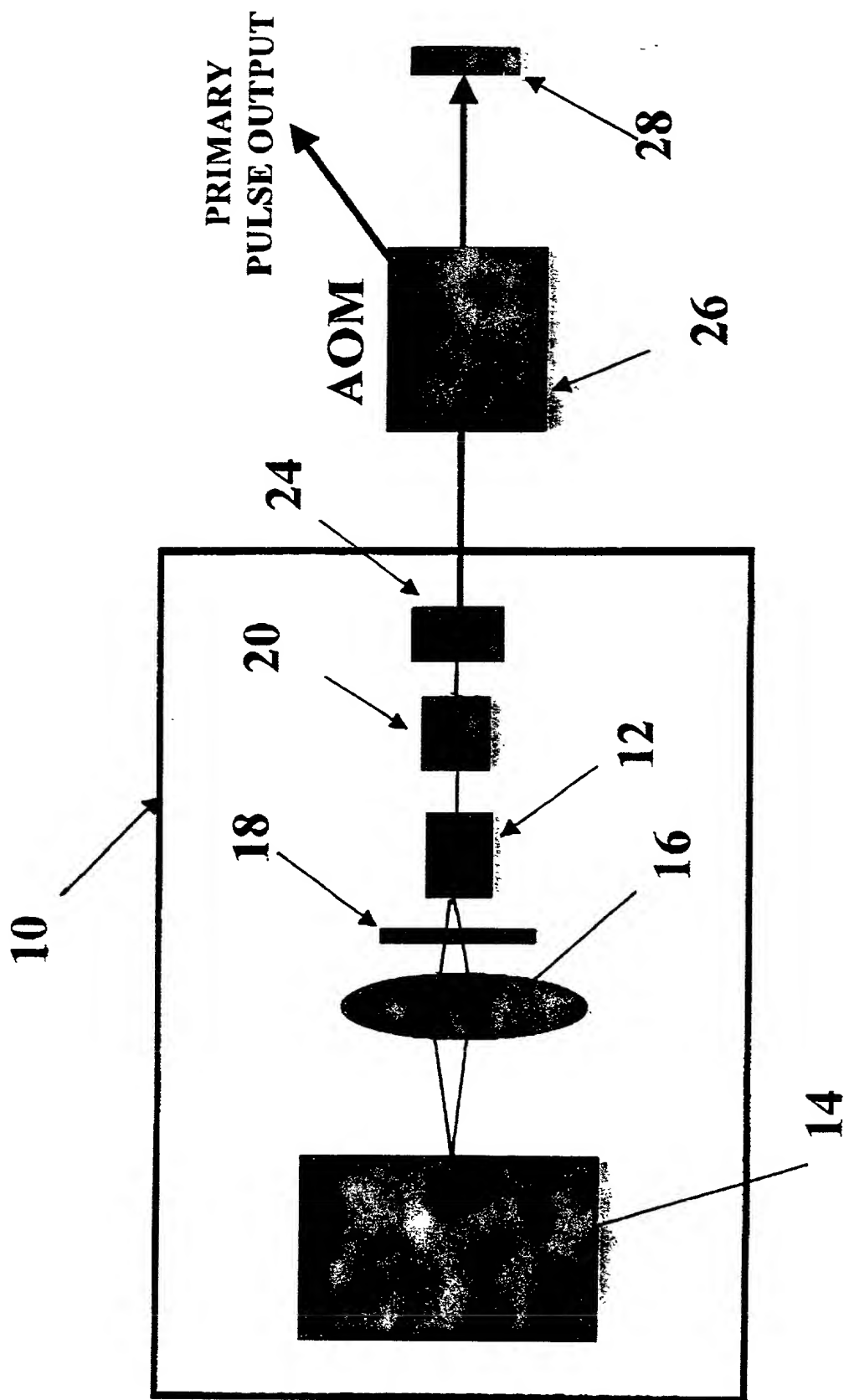


FIGURE 1

FIG. 4

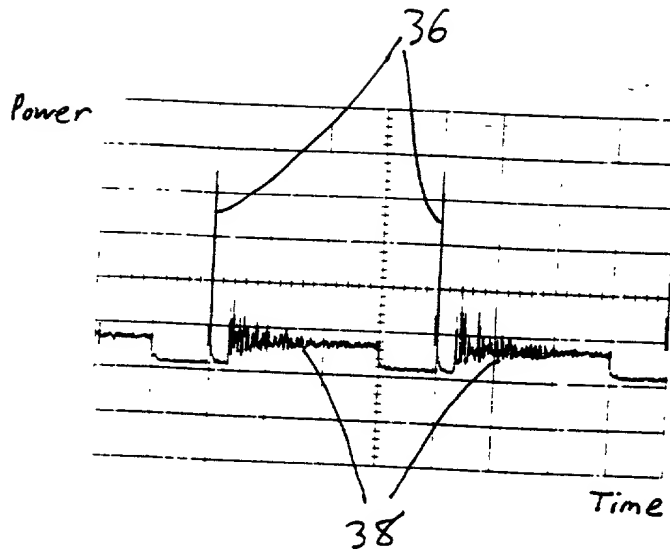


FIG. 5

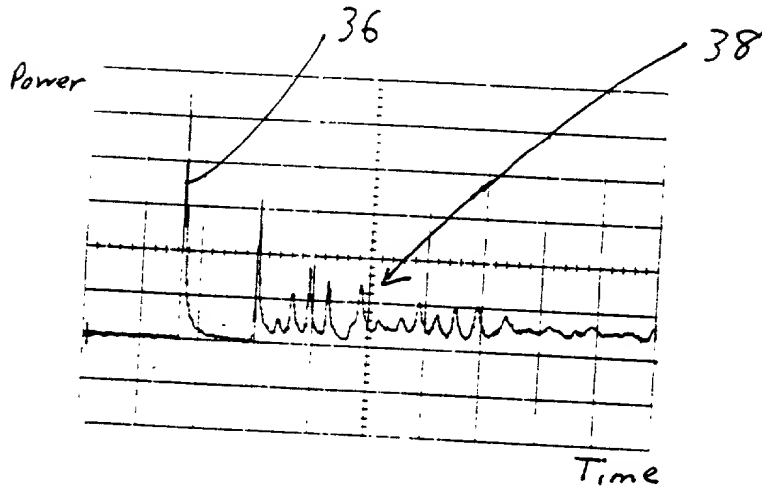
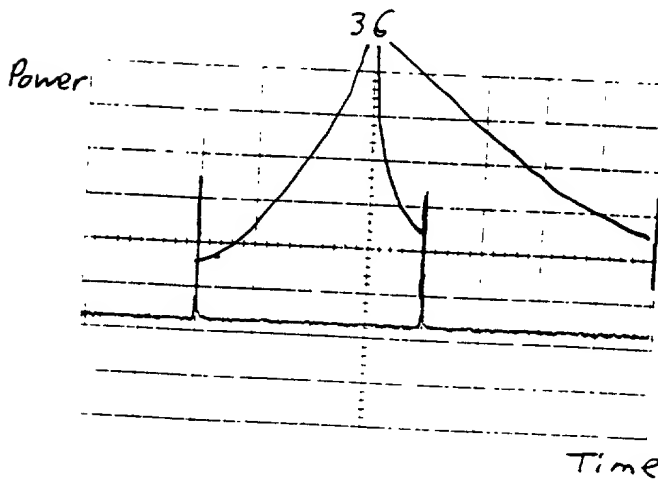


FIG. 6



COMBINED DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled PULSE CONTROL IN LASER SYSTEMS, the specification of which ☒ is attached hereto.

- ☐ was filed on _____ as Application Serial No. _____
and was amended on _____.
☐ was described and claimed in PCT International Application No. _____
filed on _____ and as amended under PCT Article 19 on _____.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose all information I know to be material to patentability in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby appoint the following attorneys and/or agents to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith: James E. Mrose, Reg. No. 33,264; John N. Williams, Reg. No. 18,948

Address all telephone calls to James E. Mrose at telephone number 617/542-5070.

Address all correspondence to James E. Mrose, Fish & Richardson P.C., 225 Franklin Street ,
Boston, MA 02110-2804.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

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